

# EDERC 2014 Technical Panel Committee



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## CALL FOR PAPERS DEADLINE HAS BEEN EXTENDED TO 16TH JUNE

Ahmed Amein	Military Technical College, Cairo
Geneviève Baudoin	ESIEE
Holger Blume	Leibniz Universitaet Hannover
Frank Bormann	University of Applied Sciences Zwickau
Neven Bulic	University of Rijeka Faculty of Engineering
Lorenzo Capineri	University of Florence
Jonathon Chambers	Loughborough University
Naim Dahnoun	University of Bristol
Jacob Fainguelernt	Tel-Aviv University
Vittorio Ferrari	University of Brescia
Alexander Frey	University of Applied Sciences Augsburg
Woon Seng Gan	Nanyang Technological University
Pedro Gaspar	University of Beira Interior
Wolfgang Gruber	Johannes Kepler University Linz
Derrick Holliday	University of Strathclyde
Iain Hunter	Texas Instruments
Gianluca Ippoliti	Università Politecnica delle Marche
Edward Jones	National University of Ireland, Galway
Martin Judd	University of Strathclyde
Sotiris Karabetos	Technological Educational Institute (TEI) of Athens
Peter Karsmakers	Katholieke Universiteit Leuven
Sascha Kuehl	Technische Universitaet Muenchen
Claus Kuntzsch	Technische Hochschule Nuernberg Georg Simon Ohm
Yves Leduc	Polytech Nice-Sophia
Michele Magno	University of Bologna
Lucio Marcenaro	Università degli Studi di Genova
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Franz Quint	University of Applied Sciences Karlsruhe
Olli Silvén	University of Oulu
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Jarmo Takala	Tampere University of Technology
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